

L Number	Hits	Search Text	DB	Time stamp
1	20704	"double side polishing" or DSP	USPAT; EPO; JPO; IBM_TDB	2003/03/24 15:22
2	2183	(grinding or grind or grinded) and (edge or circumference) and (polished or polishing or polish) and etch\$3	USPAT; EPO; JPO; IBM_TDB	2003/03/24 15:53
3	30	("double side polishing" or DSP) and ((grinding or grind or grinded) and (edge or circumference) and (polished or polishing or polish) and etch\$3)	USPAT; EPO; JPO; IBM_TDB	2003/03/24 15:24
4	432	(grinding or grind or grinded) and (edge or circumference) and (polished or polishing or polish) and etch\$3 and (testing ot testedor metrology)	USPAT; EPO; JPO; IBM_TDB	2003/03/24 16:02
5	52	((grinding or grind or grinded) and (edge or circumference) and (polished or polishing or polish) and etch\$3 and (testing ot testedor metrology)) and 438/\$.ccls.	USPAT; EPO; JPO; IBM_TDB	2003/03/24 16:00
6	192	((grinding or grind or grinded) and (edge or circumference) and (polished or polishing or polish) and etch\$3 and (testing ot testedor metrology)) and semiconductor	USPAT; EPO; JPO; IBM_TDB	2003/03/24 16:00
7	271	(grinding or grind or grinded) and (edge or circumference) and (polished or polishing or polish) and etch\$3 and (cluster or module)	USPAT; EPO; JPO; IBM_TDB	2003/03/24 16:52
9	1	6309279.pn.	USPAT; EPO; JPO; IBM_TDB	2003/03/24 16:50
11	13	(grinding or grind or grinded) and (bevel or beveling) and (polished or polishing or polish) and etch\$3 and (cluster or module)	USPAT; EPO; JPO; IBM_TDB	2003/03/24 16:54
12	146	(grinding or grind or grinded) and (bevel or beveling) and (polished or polishing or polish) and etch\$3	USPAT; EPO; JPO; IBM_TDB	2003/03/24 16:58
13	30	("double side polishing" or DSP) and(grinding or grind or grinded) and (clean or cleaning or rinse or rinsing) and (polished or polishing or polish) and etch\$3	USPAT; EPO; JPO; IBM_TDB	2003/03/24 17:01